Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4 High Tg	8.00mil	4.2	
5	Signal Layer 1	Copper	1.40mil		
6	Dielectric 2	FR-4 High Tg	40.00mil	4.2	
7	Signal Layer 2	Copper	1.40mil		
8	Dielectric 3	FR-4 High Tg	8.00mil	4.2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				